

RULE 202. EXEMPTIONS TO RULE 201. (Adopted 10/18/1971, revised 5/1/1972 and 6/27/1977, readopted 10/23/1978, revised 12/7/1987, 1/11/1988, 1/17/1989, 7/10/1990, 7/30/1991, 11/05/1991, 3/10/1992, 5/10/1994, 6/28/1994, 4/17/1997, 3/17/2005, 1/17/2008, 6/19/2008, and 9/20/2010, and [date of amended rule adoption])

[...]

D. General Provisions

[...]

7. Stationary Source Permit Exemption

A permit shall not be required for any new, modified or existing stationary source if the uncontrolled actual emissions of each individual affected pollutant from the entire stationary source are below 1.00 ton per calendar year, unless:

[...]

e. the source is a new or modified source which emits hazardous air emissions and is located within 1,000 feet from the outer boundary of a school site (Health and Safety Code Section 42301.6, *et seq.*); or

f. the source is subject to one or more of the following California Code of Regulations, Title 17, Division 3, Subchapter 10, Article 4, Regulations to Achieve Greenhouse Gas Emission Reductions:

1. Subarticle 2, Semiconductors and Related Devices (Section 93420 *et seq.*) in effect [date of amended rule adoption].

2. Subarticle 6, Methane Emissions from Municipal Solid Waste Landfills (Section 95460 *et seq.*) in effect [date of amended rule adoption].

[...]

T. Semiconductor and Electronics Manufacturing Equipment and Operations

The following semiconductor and electronics manufacturing equipment and operations is exempt from permit requirements. Notwithstanding the listed exemptions, any collection of articles, machines, equipment or other contrivances within each listed equipment category at a stationary source that has aggregate emissions in excess of one ton per calendar year of any affected pollutant is not exempt. Notwithstanding the listed exemptions, any article, machine, equipment or other contrivance that utilizes or creates fluorinated gas(es) or uses fluorinated heat transfer fluids is not exempt.

1. Vacuum deposition.
2. Ion implantation.
3. Sputtering.
4. Ozone/plasma/ion etching or ashing.
5. Vacuum bake systems.

[draft of January 25, 2011]

6. Furnaces used for crystal growth, liquid phase epitaxial, compounding and/or refining, and carbon coating.
7. Automated epoxy adhesive, potting compound, conformal coating dispensing machines and associated equipment used for mixing, injection and curing.
8. Ovens used exclusively for curing epoxies and adhesives. Ovens used exclusively for curing permitted paint application processes.
9. Ovens for drying parts cleaned with water.

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[...]

V. Storage and Transfer Equipment and Operations

| The following storage and transfer equipment and operations ~~is~~are exempt from permit requirements.

[...]